



SOT78D

plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	TO-220AB
Package type industry code	TO-220AB
Package style descriptive code	SFM (single-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	3-lead TO-220AB
JEITA package outline code	SC-46
Mounting method type	H (heatsink mount)
Issue date	10-7-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		15.2	-	15.6	16	mm
E	package width		9.7	-	10	10.3	mm
A	seated height		4.3	-	4.5	4.7	mm
e	nominal pitch		-	-	2.54	-	mm
n ₂	actual quantity of termination		-	-	3	-	



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2. Package outline

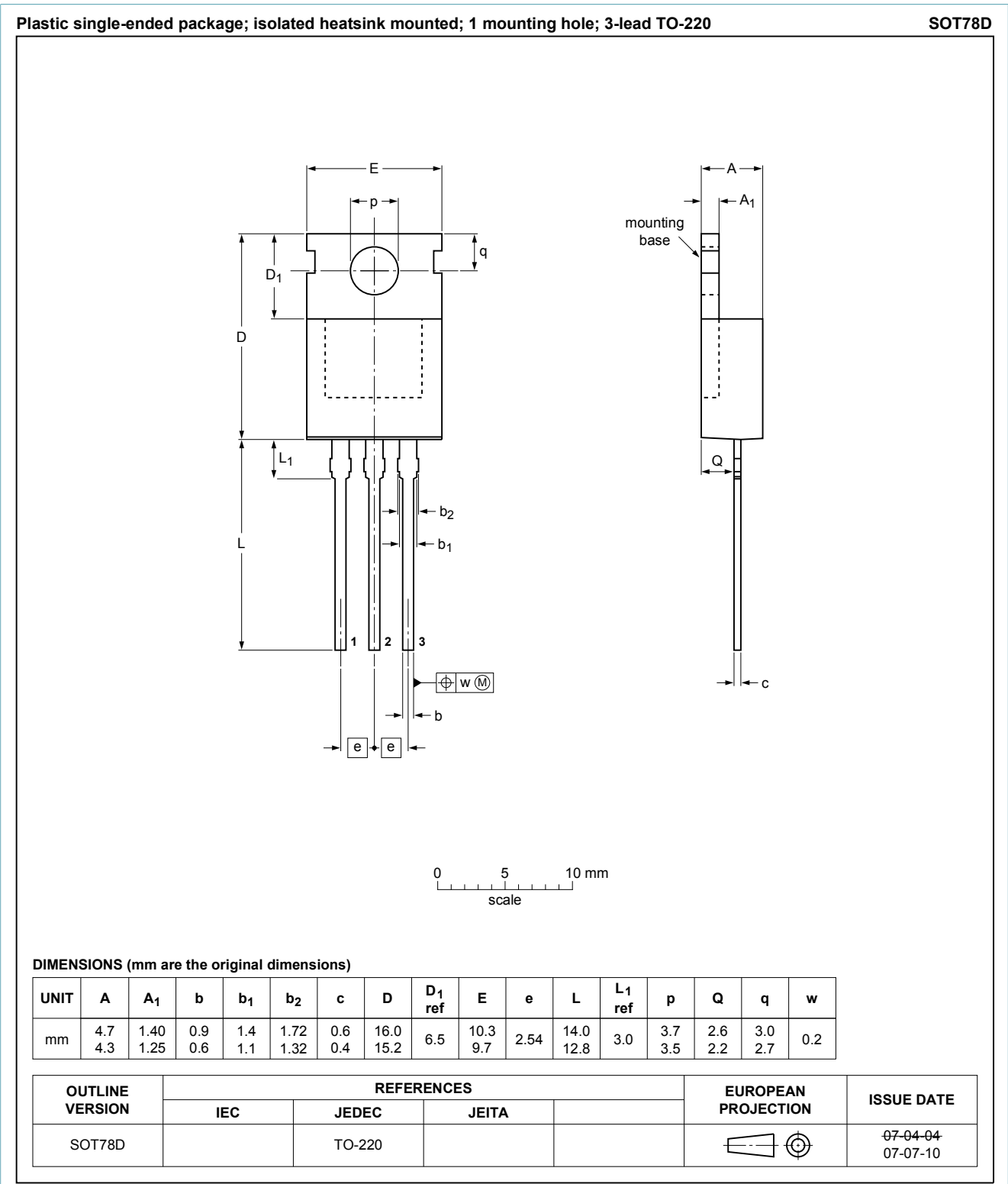


Fig. 1. Package outline TO-220AB (SOT78D)

3. Legal information

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